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- Controlled Baseline

   One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- 3-State Version of 'HC153
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Inverting Outputs Drive Up To 15 LSTTL Loads

<sup>†</sup> Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Low Power Consumption, 80-μA Max I<sub>CC</sub>**
- Typical t<sub>pd</sub> = 9 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Permit Multiplexing From n Lines to One Line
- Perform Parallel-to-Serial Conversion

D PACKAGE (TOP VIEW)										
10E	1	Ο	16	] V <sub>CC</sub>						
B	2		15	] 2OE						
1C3	3		14	] A						
1C2	4		13	] 2C3						
1C1	5		12	] 2C2						
1C0	6		11	] 2C1						
1C0	7		10	] 2C0						
SND	8		9	] 2Y						

### description/ordering information

Each data selector/multiplexer contains inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate output-control inputs are provided for each of the two 4-line sections.

The 3-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (in the high-impedance state), the low impedance of the single enabled output drives the bus line to a high or low logic level. Each output has its own output-enable ( $\overline{OE}$ ) input. The outputs are disabled when their respective  $\overline{OE}$  is high.

### **ORDERING INFORMATION**

TA	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Tape and reel	SN74HC253QDREP	SHC253QEP

<sup>‡</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



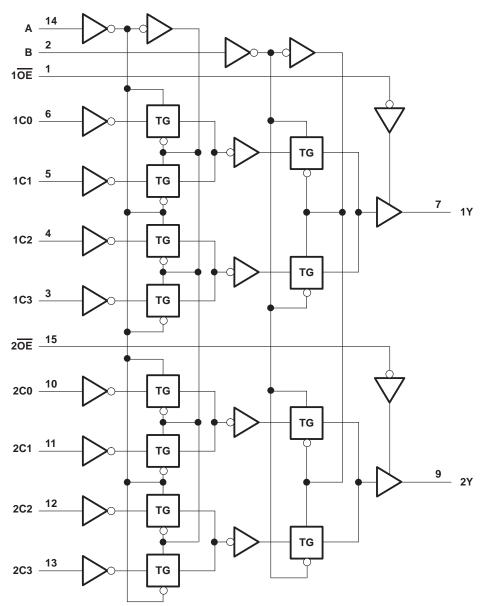
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	FUNCTION TABLE											
			INPUTS									
SELE	ЕСТ†		DA	TA		OE	OUTPUT					
В	Α	C0	C1	C2	C3	OE						
Х	Х	Х	Х	Х	Х	н	Z					
L	L	L	Х	Х	Х	L	L					
L	L	Н	Х	Х	Х	L	Н					
L	Н	Х	L	Х	Х	L	L					
L	Н	Х	Н	Х	Х	L	Н					
н	L	Х	Х	L	Х	L	L					
н	L	Х	Х	Н	Х	L	Н					
н	Н	Х	Х	Х	L	L	L					
н	Н	Х	Х	Х	Н	L	Н					

 $\ensuremath{^\dagger}$  Select inputs A and B are common to both sections.



logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2)	73°C/W
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	V	
		$V_{CC} = 2 V$	1.5				
ViH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			V	
		V <sub>CC</sub> = 6 V	4.2				
		$V_{CC} = 2 V$			0.5		
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35	1.35 V	
		V <sub>CC</sub> = 6 V			1.8		
$\vee_{I}$	Input voltage		0		VCC	V	
VO	Output voltage		0		VCC	V	
		$V_{CC} = 2 V$			1000		
$\Delta t / \Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500	ns	
		V <sub>CC</sub> = 6 V			400		
Т <sub>А</sub>	Operating free-air temperature		-40		125	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;			
PARAMETER	TEST CONE	DITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
	l <sub>OH</sub> = -20 μA		2 V	1.9	1.998		1.9		
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		
∨он	VI = VIH or VIL		6 V	5.9	5.999		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		
		I <sub>OH</sub> = -7.8 mA	6 V	5.48	5.8		5.2		
			2 V		0.002	0.1		0.1	
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1	
VOL			6 V		0.001	0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4	1
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4	
lj	VI = ACC  or  0		6 V		±0.1	±100	ł	±1000	nA
I <sub>OZ</sub>	VO = ACC or 0		6 V		±0.01	±0.5		±10	μΑ
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160	μΑ
Ci			2 V to 6 V		3	10		10	pF

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то	N	Т	ן = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MAX	UNIT	
			2 V		62	150	225		
	A or B	Any Y	4.5 V		19	30	45		
4			6 V		16	26	38		
<sup>t</sup> pd	5.		2 V		54	126	210	ns	
	Data (Any C)	Y	4.5 V		16	28	42		
	(/ (/) ())		6 V		13	23	36		
			2 V		28	100	150	ns	
<sup>t</sup> en	OE	Y	4.5 V		11	20	30		
			6 V		9	17	26		
			2 V		21	135	203		
<sup>t</sup> dis	OE	Y	4.5 V		14	30	45	ns	
			6 V		12	35	38		
			2 V		28	60	90		
tt		Y	4.5 V		8	12	18	ns	
			6 V		6	10	15		



# switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		T,	<b>₄ = 25°C</b>	;				
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN M/	4X	UNIT	
			2 V		76	235	3	55		
	A or B	Any Y	4.5 V		23	47		71		
<sup>t</sup> pd			6 V		20	41		60	ns	
	Data (Any C)		2 V		68	220	3	35		
		Y	4.5 V		20	44		67		
			6 V		17	38		57		
			2 V		44	185	2	80		
<sup>t</sup> en	OE	Y	4.5 V		16	37		56	ns	
-			6 V		14	32		48		
			2 V		45	210	3	15		
tt		Y	4.5 V		17	42		63	ns	
			6 V		13	36		53		

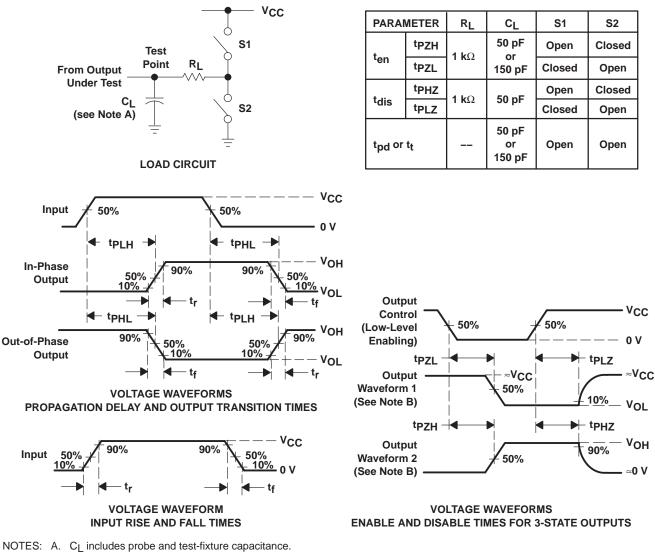
### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per multiplexer	No load	45	pF



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- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F.  $t_{P7I}$  and  $t_{P7H}$  are the same as  $t_{en}$ .
- G. tpLH and tpHL are the same as  $t_{pd}$ .





### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74HC253QDREP	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04699-01XE	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74HC253-EP :

- Catalog: SN74HC253
- Automotive: SN74HC253-Q1
- Military: SN54HC253

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC253QDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



### PACKAGE MATERIALS INFORMATION

5-Nov-2008

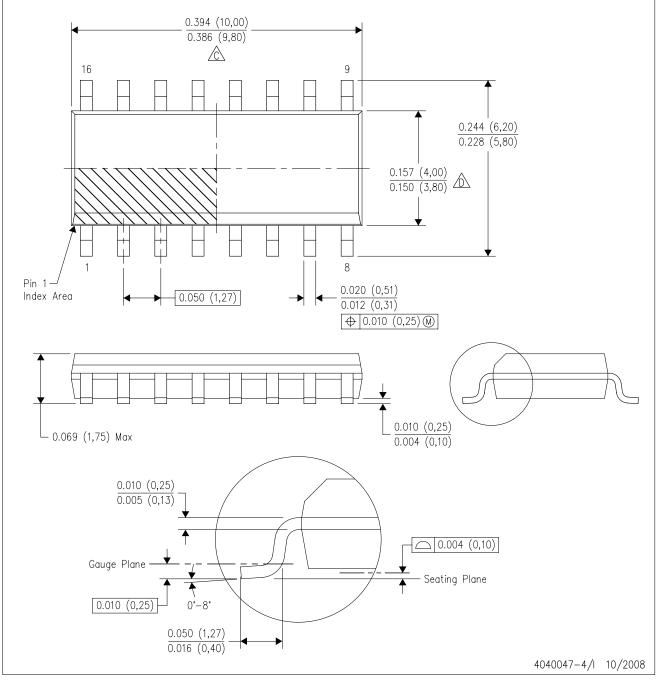


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC253QDREP	SOIC	D	16	2500	333.2	345.9	28.6

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.



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